

## Sequential 4G-Bits XtraROM for Amusement

### 1. FEATURES

- Organization
  - 256M x 16bit
  - Page Size : 512words(support sequential read)
- Memory Area: Please refer to "7. MEMORY AREA"
- Read Operation
  - Latency : 15us
  - Read Cycle Time : 40ns
- Voltage Supply : 3.0V ~ 3.6V
- Current
  - Read : 120mA
  - Stand-by : 200uA
- Command/Address/Data Multiplexed Port
- Package : 70-pin SSOP
- All devices are RoHS compliant

### 2. GENERAL DESCRIPTION

The MX23J4G76 is a single 3.3V XtraROM, density 4Gbit, factory pre-programmed ROM with Macronix NBit technology.

It utilizes the 16 bit multiplexed I/O bus for command, address, and data inputs/outputs.

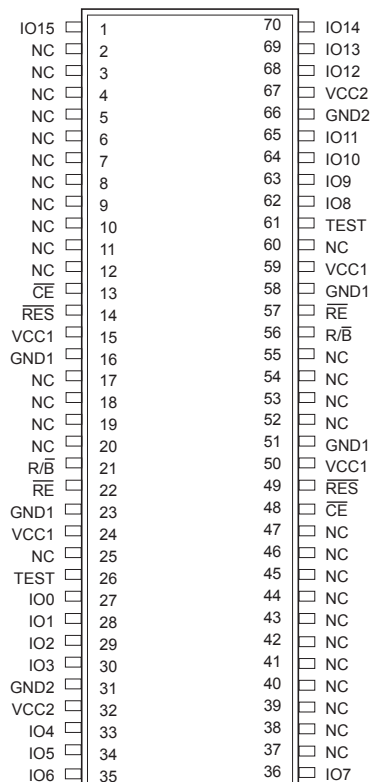
Simple design structure makes the cost of the device and competitive over the other types of code-storage memory IC.

### 3. ORDER INFORMATION

Part No.	Read Cycle Time	Package
MX23J4G76MC-40G	40ns	70 SSOP

### 4. PIN CONFIGURATIONS

#### 70 SSOP



### 5. PIN DESCRIPTION

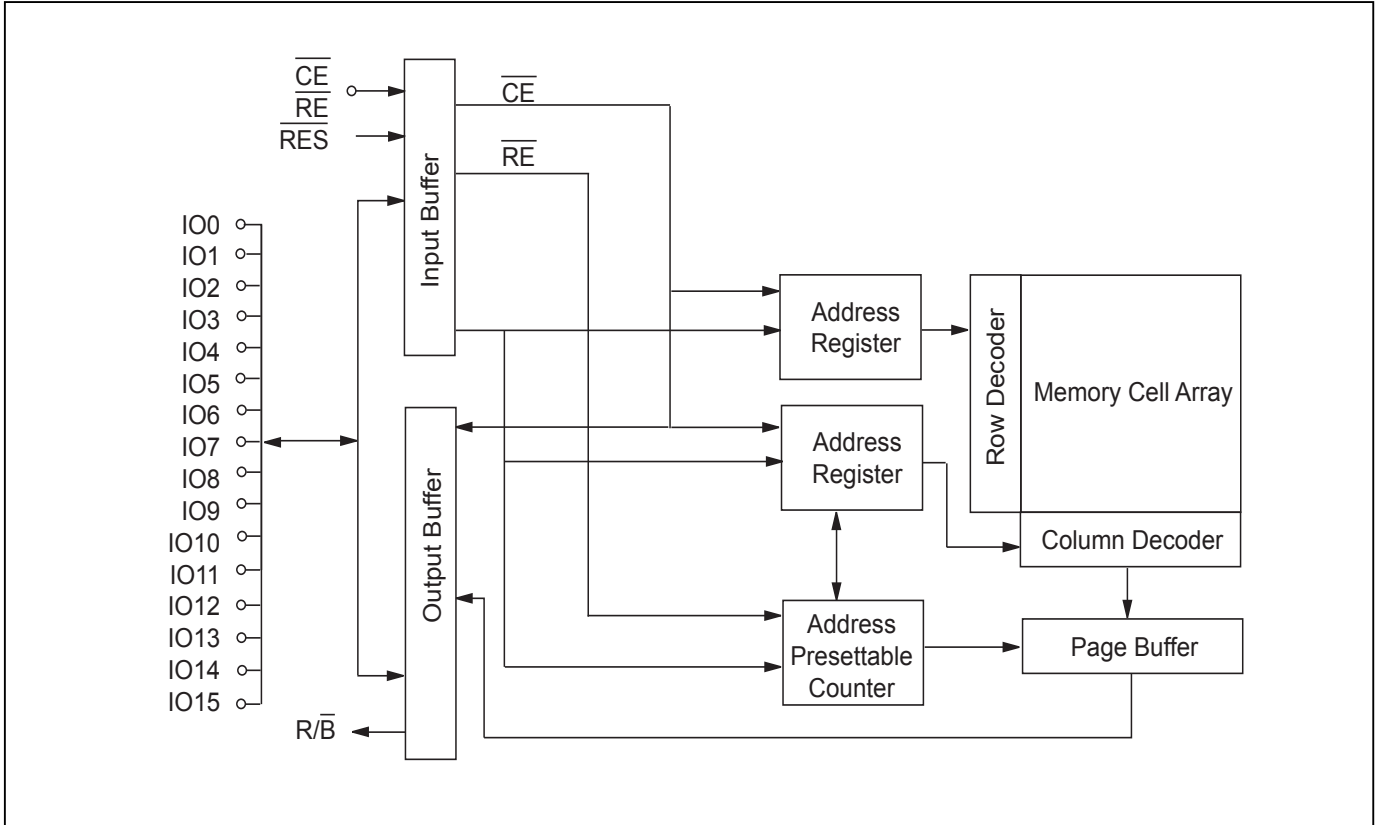
Symbol	Type	Pin Function
$\overline{CE}$	I	Chip Enable
IO0~IO15	I/O	Command / Address / Data Multiplexed I/O Port
$\overline{RE}$	I	Read Clock
VCC1	I	Power (3.3V)
VCC2	I	Power (3.3V, for I/O)
GND1	I	Ground
GND2	I	Ground (for I/O)
NC (Note 3)		All pins = Connected to Floating All pins = Connected to GND
R/B	OD	Ready/Busy output pin (Note 1)
$\overline{RES}$	I	RESET (Low Active)
TEST	I	Test Pin (Note 2)

Note 1 : R/B (2 pins)=connected in PC board.  
R/B open drain.

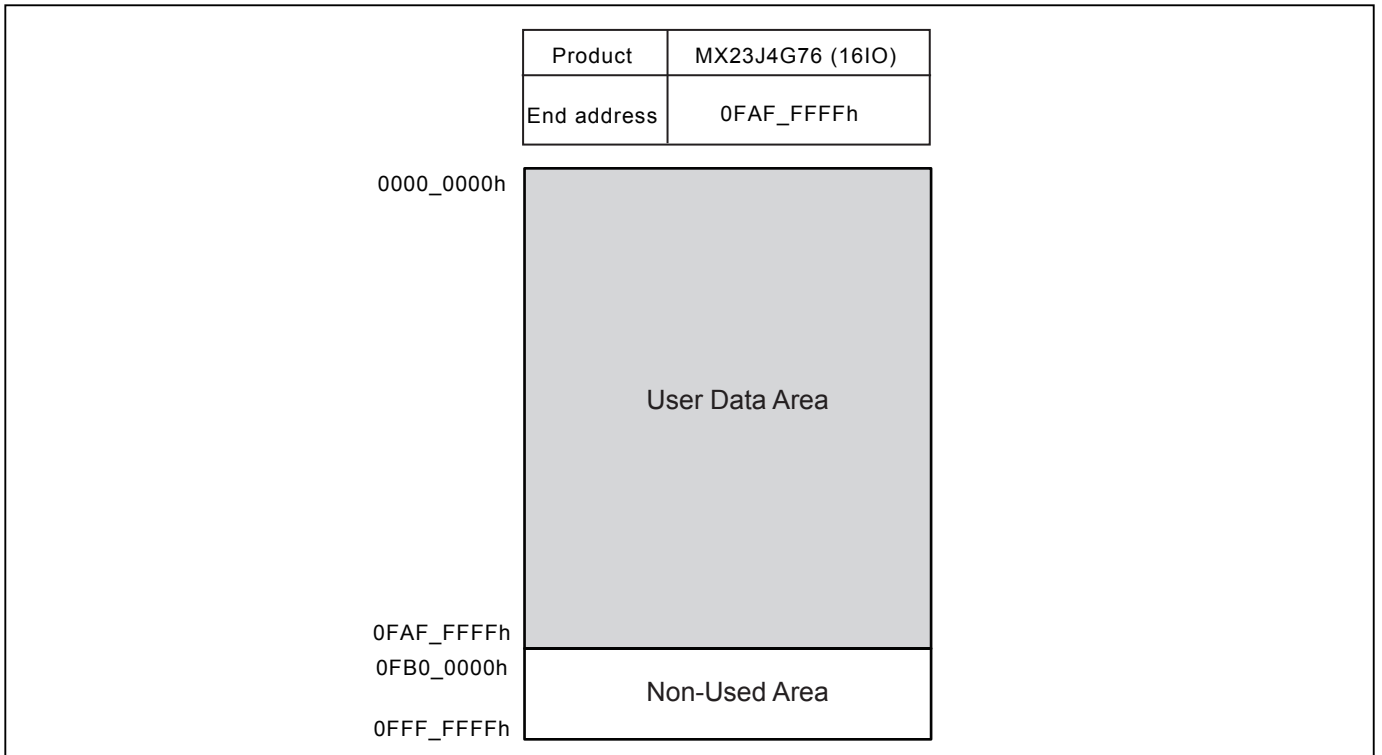
Note 2 : TEST pin can be connected to GND, VCC or Open.

Note 3 : All NC pins = Connected to Floating  
or All NC pins = Connected to GND

**6. BLOCK DIAGRAM**



**7. MEMORY AREA**



## 8. ABSOLUTE MAXIMUM RATINGS

Item	Symbol	Ratings
Voltage on any Pin Relative to VSS	$V_{IN}$	-0.5V to 4.6V
Ambient Operating Temperature	$T_{opr}$	0°C to 85°C
Storage Temperature	$T_{stg}$	-55°C to 125°C

## 9. DC CHARACTERISTICS

Table 1. DC Characteristics (  $T_{opr} = 0\sim 85^{\circ}\text{C}$ ,  $V_{CC} = 3.0\sim 3.6\text{V}$  )

Item	Symbol	Test Conditions	Min.	Max.	Unit
Input High Voltage	$V_{IH}$	-	2	$V_{CC}+0.5\text{V}$	V
Input Low Voltage	$V_{IL}$	-	-0.5	0.8	V
Output High Voltage	$V_{OH}$	$I_{OH} = -400\mu\text{A}$	2.4	-	V
Output Low Voltage	$V_{OL}$	$I_{OL} = 1.6\text{mA}$	-	0.4	V
Operating Current *	$I_{CC}$	$\overline{CE} = V_{IL}$ , $I_{OUT} = 0\text{mA}$ , $t_{CS} = 100\text{ns}$ , $t_{CH} = 100\text{ns}$ , $t_{CEPH} = 100\text{ns}$ , $t_{CYC} = 50\text{ns}$ , $t_{WH} = 25\text{ns}$ , $t_{WL} = 25\text{ns}$	-	120	mA
Standby Current (CMOS)	$I_{STB}$	$\overline{CE} = V_{CC} - 0.2\text{V}$ , IO=Hi-z, $RE = V_{CC} - 0.2\text{V}$	-	200	$\mu\text{A}$
Input Leakage Current	$I_{LI}$	$V_{IN} = 0$ to $V_{CC}(\text{max})$	-	$\pm 10$	$\mu\text{A}$
Output Leakage Current	$I_{LO}$	$V_{OUT} = 0$ to $V_{CC}(\text{max})$	-	$\pm 10$	$\mu\text{A}$

\* note: output load : 30pF

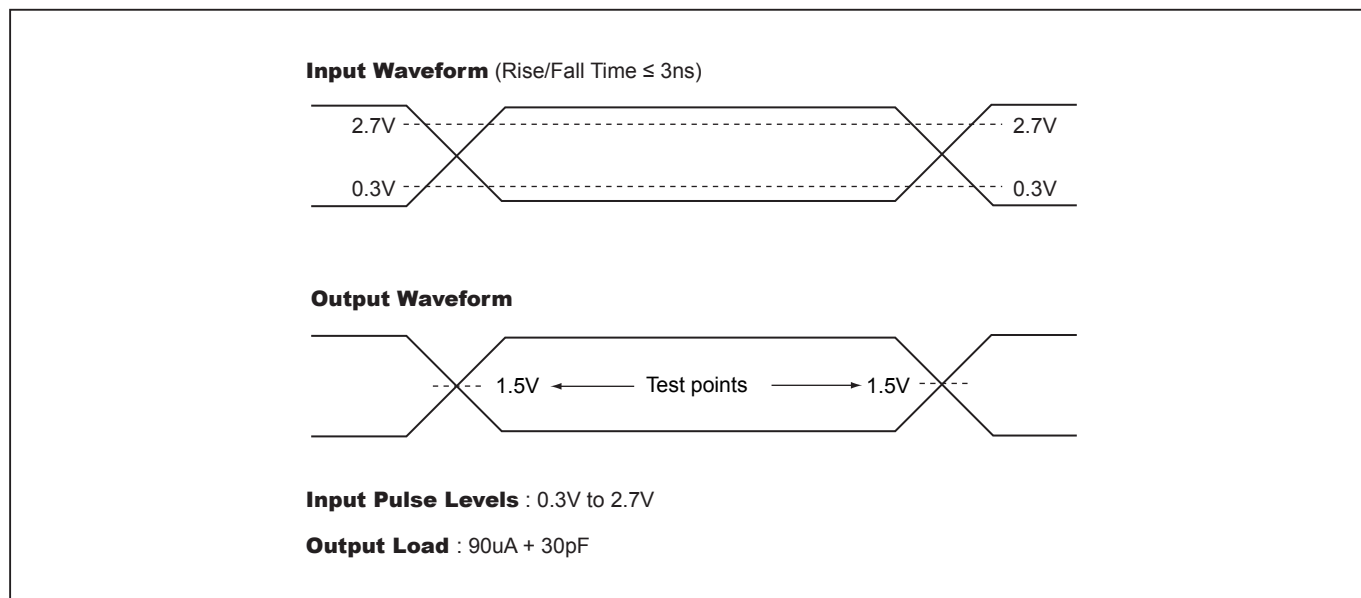
\* Recommended Operation Condition, Vcc Rise Time 30mV/mS

## 10. AC CHARACTERISTICS

**Table 2. AC TEST CONDITION**

Parameter	Test Condition
Input Pulse Level	0.3V to 2.7V
Input Rise and Fall Times	3ns
Output Timing Levels	1.5V/1.5V
Output Load	90uA + 30pF

### AC Test Conditions

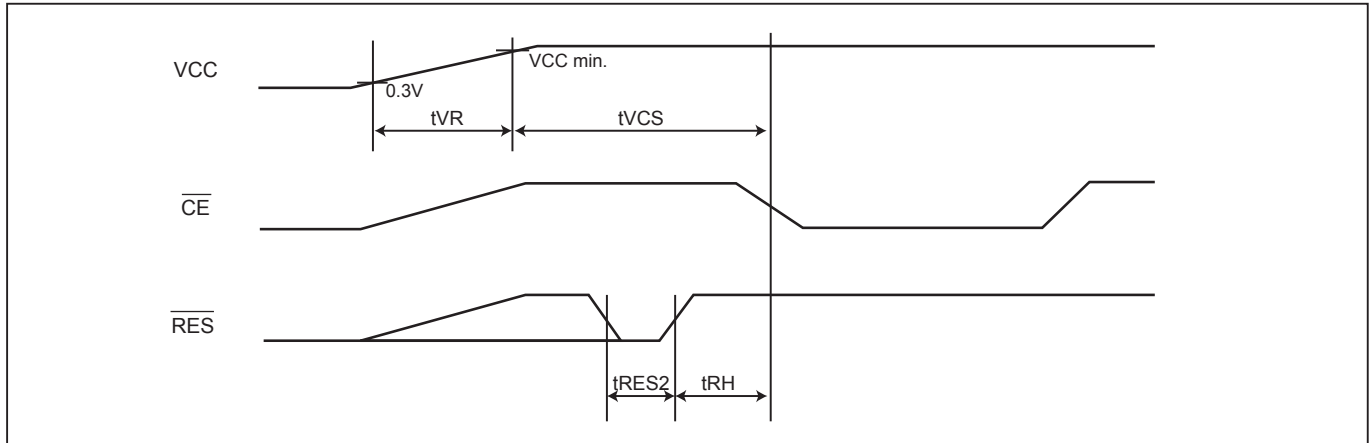


**Table 3. AC Characteristics for Command Input ( $T_{opr} = 0\sim 85^{\circ}\text{C}$ ,  $V_{CC} = 3.0\sim 3.6\text{V}$ )**

Parameter	Symbol	Min.	Unit
$\overline{\text{CE}}$ Setup Time	$t_{CS}$	50	ns
$\overline{\text{CE}}$ Hold Time	$t_{CH}$	50	ns
$\overline{\text{CE}}$ High Pulse Width	$t_{CEPH}$	100	ns
Data-in Setup Time	$t_{DIS}$	5	ns
Data-in Hold Time	$t_{DIH}$	5	ns
Data-out Hold Time *	$t_{DOH}$	10	ns
Read cycle time	$t_{CYC}$	40	ns
$\overline{\text{RE}}$ High Pulse Width	$t_{WH}$	16	ns
$\overline{\text{RE}}$ Low Pulse Width	$t_{WL}$	20	ns
Ready to $\overline{\text{RE}}$ low	$t_{RR}$	20	ns
$\overline{\text{RES}}$ Low Pulse Width	$t_{RES}$	100	ns
$\overline{\text{RES}}$ High Time Before Read	$t_{RH}$	1	ms

\*  $\overline{\text{RES}}$  filter glitch which pulse width is less than 5ns.

**POR SEQUENCE**



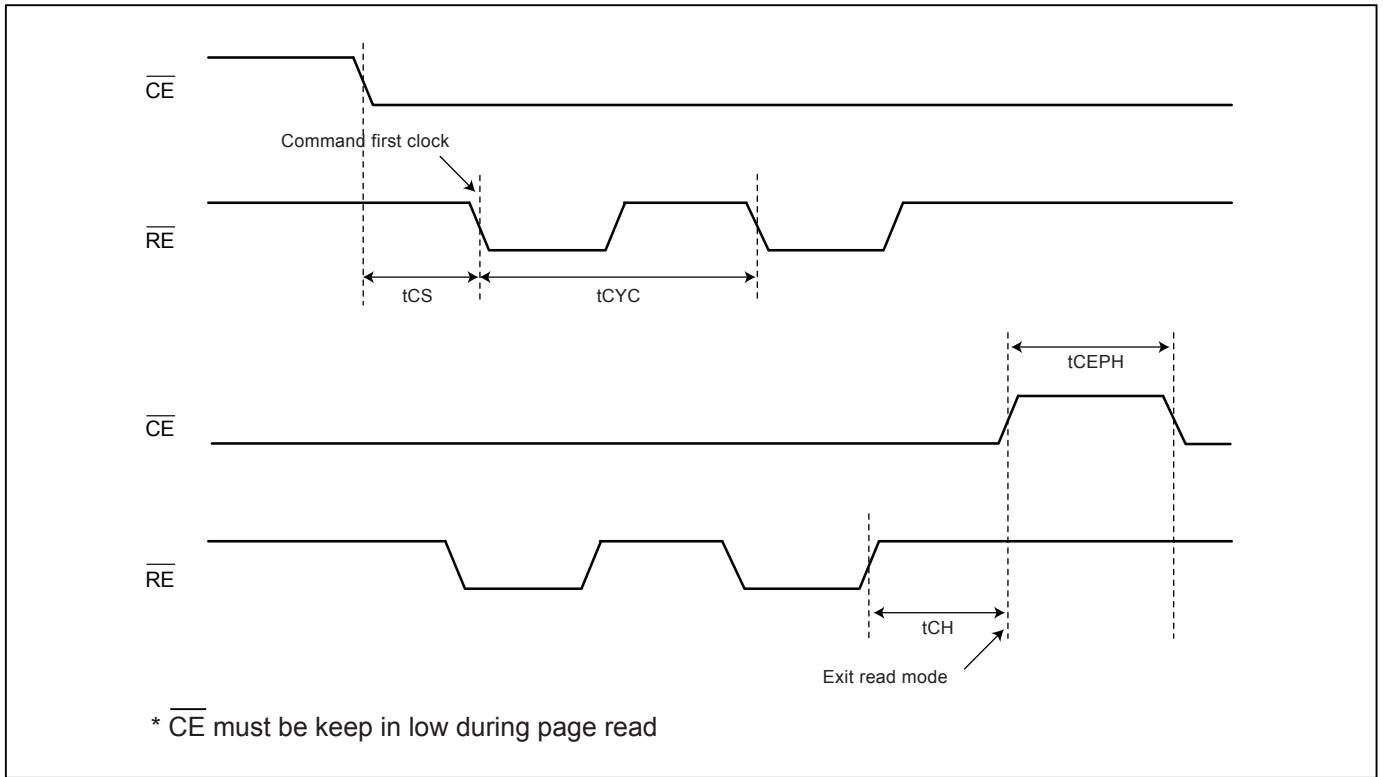
**POR Timing Waveform**

Symbol	Parameter	Min.	Max.	Unit
$t_{VR}$	VCC Rise Time	50	500000	us/V
$t_R$	Input Signal Rise Time		20	us/V
$t_F$	Input Signal Fall Time		20	us/V
$t_{VCS}$	VCC Setup Time	2		ms
$t_{RES2}$	$\overline{RES}$ Low Time 2	100		ns
$t_{RH}$	$\overline{RES}$ High Time Before Read	1		ms

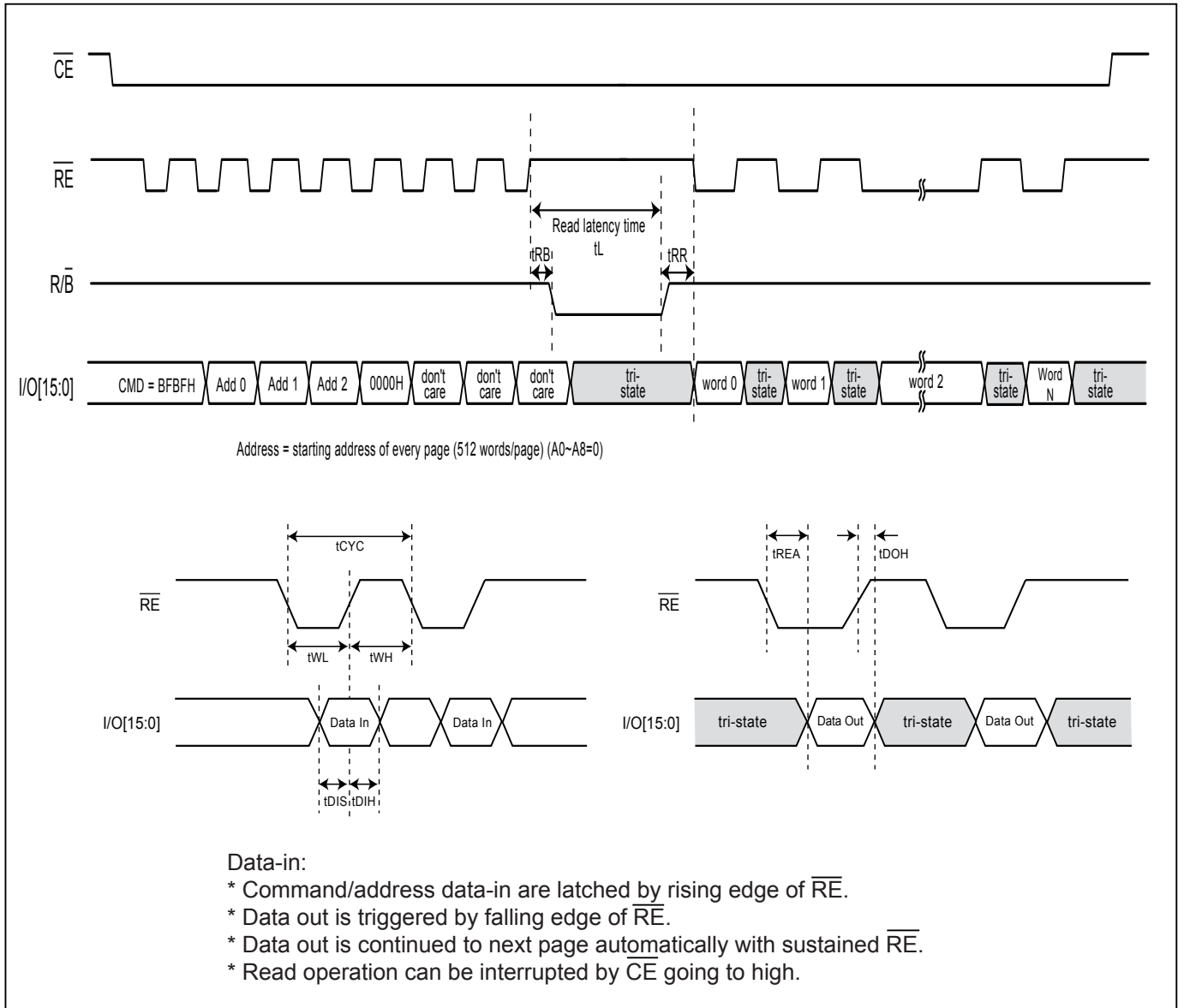
**Table 4. AC Characteristics for Data Output ( $T_{opr} = 0\sim 85^{\circ}\text{C}$ ,  $V_{CC} = 3.0\sim 3.6\text{V}$ )**

Parameter	Symbol	Min.	Max.	Unit
Read Latency Time * <sup>1</sup>	$t_L$	-	15	us
RE Access Time	$t_{REA}$	-	18	ns
RE High to Busy	$t_{RB}$	-	250* <sup>2</sup>	ns

Note: \*<sup>1</sup> The read latency will only be needed at the first page read.  
\*<sup>2</sup>  $t_{RB}=250\text{ns}$  max. including  $T_f$  at 10Kohm pull-up condition.



**AC Timing Condition**



Command Input and Data Output Timing Waveform

Table 5. Read Command Definitions

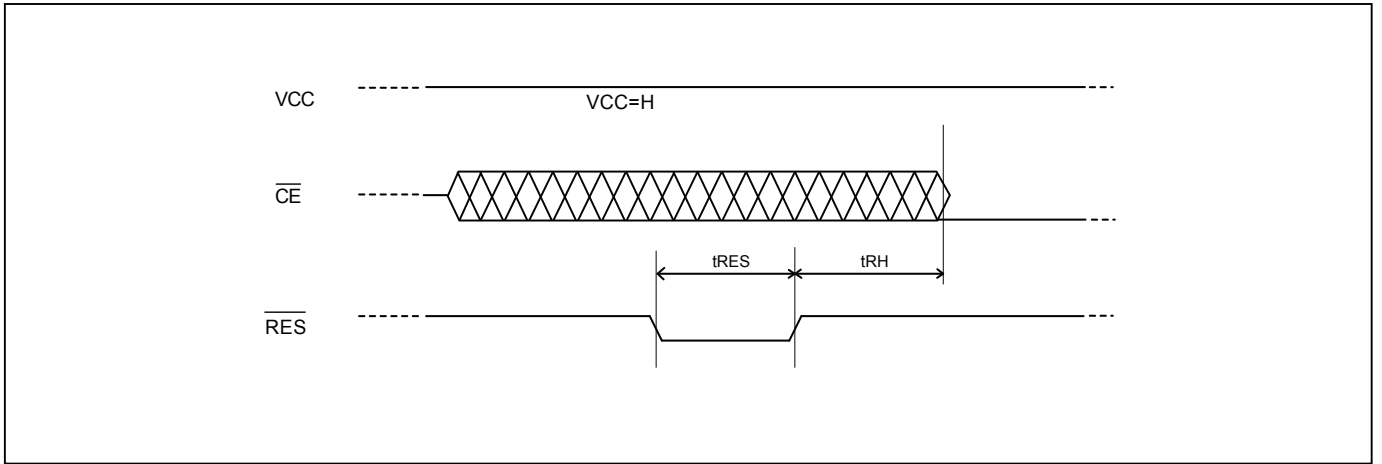
Command	Bus cycles	1st bus cycle	2nd bus cycle	3rd bus cycle	4th bus cycle	5th bus cycle	6th bus cycle	7th bus cycle	8th bus cycle
		command	address	address	address	address	address	address	address
Read Mode	8	BFBFH	Addr0	Addr1	Addr2	0000H	don't care	don't care	don't care

Addr0 : A24~A27 (IO0/8=A24, IO1/9=A25, IO2/10=A26, IO3/11=A27)

Addr1 : A16~A23 (IO0/8=A16, IO1/9=A17, IO2/10=A18, IO3/11=A19, IO4/12=A20, IO5/13=A21, IO6/14=A22, IO7/15=A23)

Addr2 : A8~A15 (IO0/8=A8, IO1/9=A9, IO2/10=A10, IO3/11=A11, IO4/12=A12, IO5/13=A13, IO6/14=A14, IO7/15=A15)

Note : The starting address of every page (A8~A0) is 0, Each page has 512 words



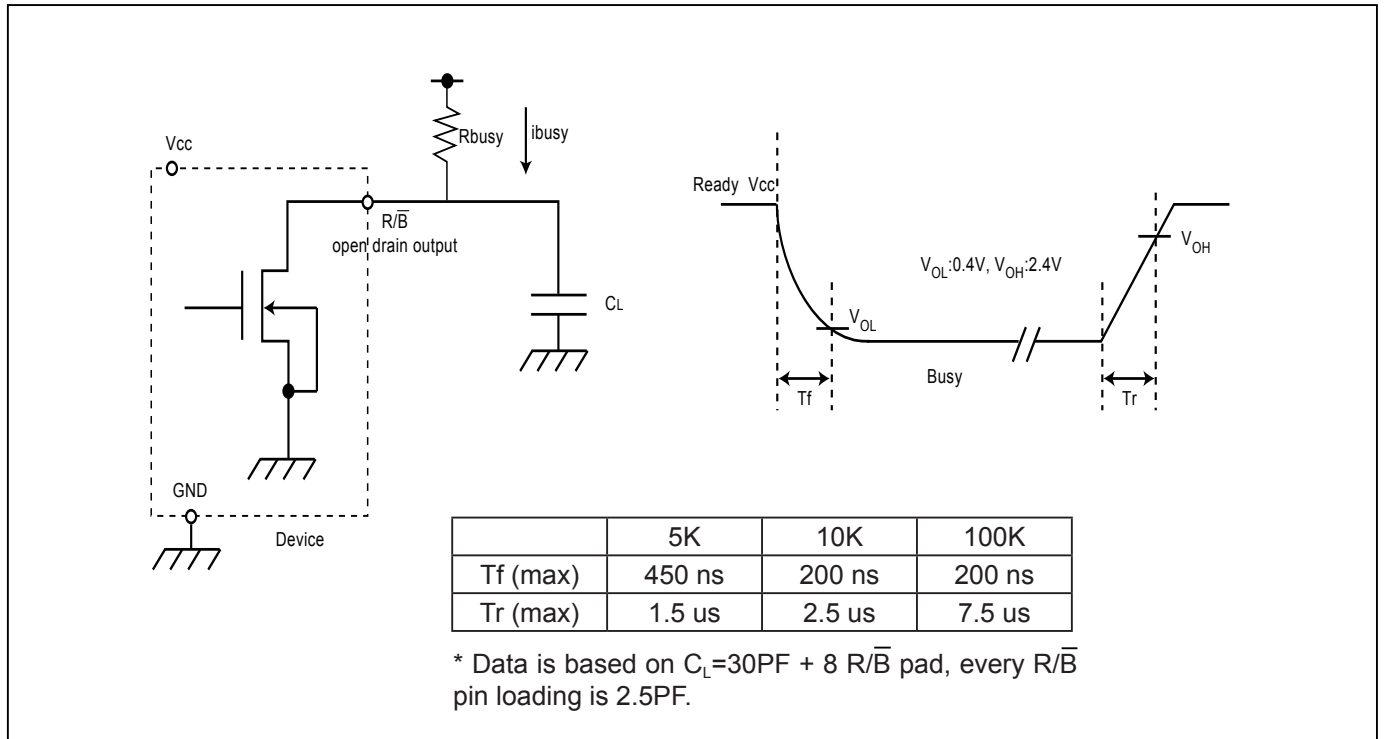
$\overline{RES}$  Timing Waveform



**READY/ $\overline{\text{BUSY}}$**

The device has a  $\overline{\text{R/B}}$  output that provides a hardware method of indicating the device is ready for read. The  $\overline{\text{R/B}}$  is normally high but transitions to low after read command is issued. It returns to high when the internal controller has finish the read operation.

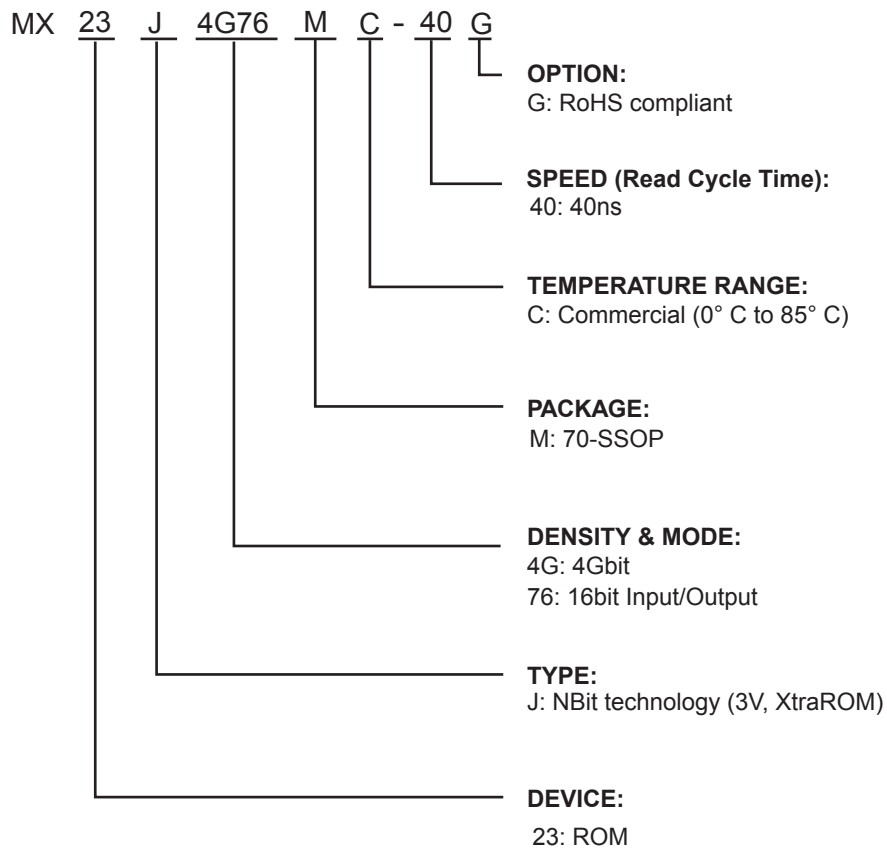
The pin is an open-drain driver thereby allowing two or more  $\overline{\text{R/B}}$  outputs to be Or-tied. A  $5\text{K}\Omega \sim 50\text{K}\Omega$  pull-up resistor is required to allow  $\overline{\text{R/B}}$  to transition high indicating the device is ready for read.



**Note:**

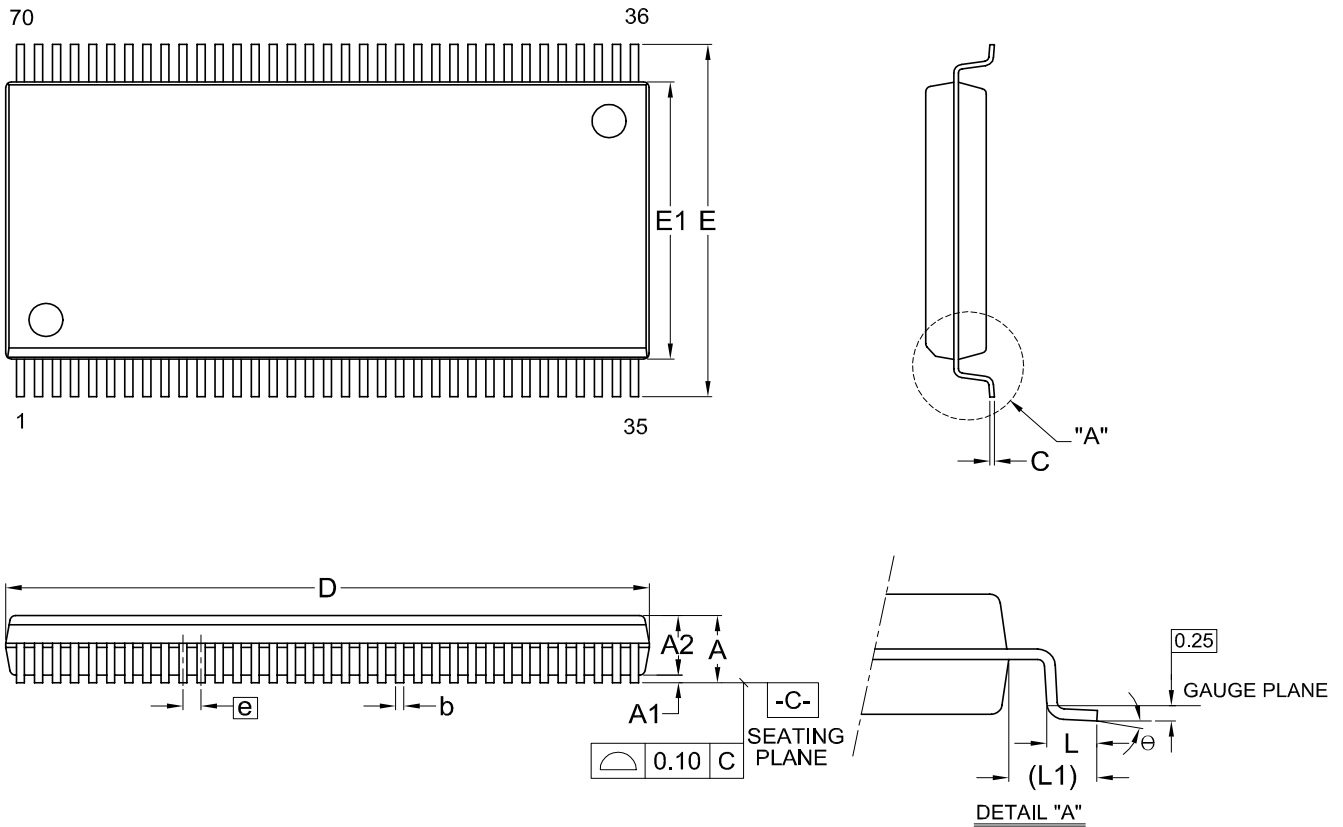
1. Rbusy must be higher than  $5\text{K}\Omega$ .
2. A schmitt trigger is suggested to provide on the user input port due to the slow slew rate of the tr and tf.

### 11. PART NAME DESCRIPTION



**12. PACKAGE INFORMATION**

Doc. Title: Package Outline for SSOP 70L (500MIL)



Dimensions (inch dimensions are derived from the original mm dimensions)

SYMBOL		A	A1	A2	b	C	D	E	E1	e	L	L1	θ
UNIT													
mm	Min.	---	0.10	2.56	0.30	0.17	28.37	15.73	12.47	---	0.61	1.51	0
	Nom.	---	0.15	2.69	0.35	0.20	28.50	16.03	12.60	0.80	0.81	1.71	5
	Max.	3.05	0.23	2.82	0.43	0.25	28.63	16.33	12.73	---	1.01	1.91	10
Inch	Min.	---	0.004	0.101	0.012	0.007	1.117	0.619	0.491	---	0.024	0.060	0
	Nom.	---	0.006	0.106	0.014	0.008	1.122	0.631	0.496	0.031	0.032	0.068	5
	Max.	0.120	0.009	0.111	0.017	0.010	1.127	0.643	0.501	---	0.040	0.075	10

Dwg. No.	Revision	Reference		
		JEDEC	EIAJ	
6110-1503	8	MO-174		

**REVISION HISTORY**

<b>Revision No.</b>	<b>Description</b>	<b>Page</b>	<b>Date</b>
0.01	1. Modified Addr0 of Table 5. Read Command Definitions	P6	NOV/18/2010
0.02	1. Added "MEMORY AREA"	P2	MAR/11/2011
0.03	1. Modified PIN CONFIGURATIONS of 70SSOP	P1	MAY/16/2011
1.0	1. Removed "ADVANCED INFORMATION"	P1	NOV/01/2011
1.1	1. Added POR SEQUENCE	P5	MAY/08/2012
	2. Added Part Name Description	P10	
	3. Modified NC1 pin (pin 26, 61) as TEST pin NC1 pin (pin 20, 55) as NC pin	P1	
	4. Modified AC Test Conditions	P4	
	5. Modified table 2 from "Input and Output Timing Levels" to "Output Timing Levels"	P4	
	6. Added note *2 for tRB	P6	

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